



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D * : Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-06-05
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Giuseppe Vitali Palma	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	7AD1*206FMM1	A	3068	2017-06-05
Amount	UoM	Unit type	ST ECOPACK Grade	
1380.00	mg	Each	ECOPACK2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	245	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	10.2-10.5-1.27	3	gull wing	
Comment	PACKAGE: D2PAK CLIP; MD VALID FOR TN2010H-6G, TN2010H-6G-TR			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)
7c-I	Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectric devices, or in a glass or ceramic matrix compound

Query : California Prop65 list, dated 27th January 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.16	Die back side metal	112
Lead	5.44	Soft solder	3943
Lead-Borate Glass	0.50	Glass coating	362

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	7AD1*206FMM1					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or Dies (choose)	Other inorganic materials	6.450	mg	supplier	die	Silicon (Si)	7440-21-3		5.689	mg	882034	4121
				supplier	metallization	Gold (Au)	7440-57-5		0.022	mg	3411	16
				supplier	Passivation	Silicon Oxide	7631-86-9		0.032	mg	4960	23
				supplier	back side metallization	Gold (Au)	7440-57-5		0.007	mg	1085	5
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.155	mg	24027	112
				supplier	glass coating	Glass : Aluminium Oxide (Al2O3)	1344-28-1		0.046	mg	7131	33
				JIG - R	glass coating	Lead-Borate Glass	65997-18-4	7c-I-Electrical and e	0.499	mg	77352	362
				supplier	alloy	Copper (Cu)	7440-50-8		899.838	mg	999000	652057
				supplier	alloy	CopperPhosphorous (CuP)	12517-41-8		0.901	mg	1000	653
				supplier	solder	Lead (Pb)	7439-92-1	7a-Lead in high met	5.441	mg	920332	3943
Leadframe	Copper & its alloys	900.739	mg	supplier	solder	Silver (Ag)	7440-22-4		0.147	mg	24865	107
				supplier	solder	Tin (Sn)	7440-31-5		0.294	mg	49729	213
				supplier	solder	Flux residue	Proprietary		0.030	mg	5074	22
				supplier	mold compound	Silica, vitreous	60676-86-0		326.009	mg	759999	236238
				supplier	mold compound	Epoxy Cresol Novolak	29680-82-2		43.754	mg	102000	31706
				supplier	mold compound	Phenol resin	9003-35-4		25.738	mg	60000	18651
Soft solder	Solder	5.912	mg	supplier	mold compound	Others	Proprietary		21.448	mg	50000	15542
				supplier	mold compound	Metal hydroxide	21645-51-2		8.579	mg	20000	6217
				supplier	mold compound	Carbon black	1333-86-4		3.432	mg	8001	2487
				supplier	solder alloy	Tin (Sn)	7440-31-5		6.314	mg	1000000	4575
Encapsulation	Other Organic Materials	428.960	mg	supplier	alloy	Copper (Cu)	7440-50-8		31.625	mg	1000000	22917
				supplier	alloy	Copper (Cu)	7440-50-8		31.625	mg	1000000	22917
				supplier	alloy	Copper (Cu)	7440-50-8		31.625	mg	1000000	22917
Connections coating	Solder	6.314	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		6.314	mg	1000000	4575
Clip	Copper & its alloys	31.625	mg	supplier	alloy	Copper (Cu)	7440-50-8		31.625	mg	1000000	22917